



Features

- Single 3.3V power supply
- Ideal for low-voltage cache memory applications
- High speed
— 12/15 ns
- Plastic SOJ and TSOP packaging

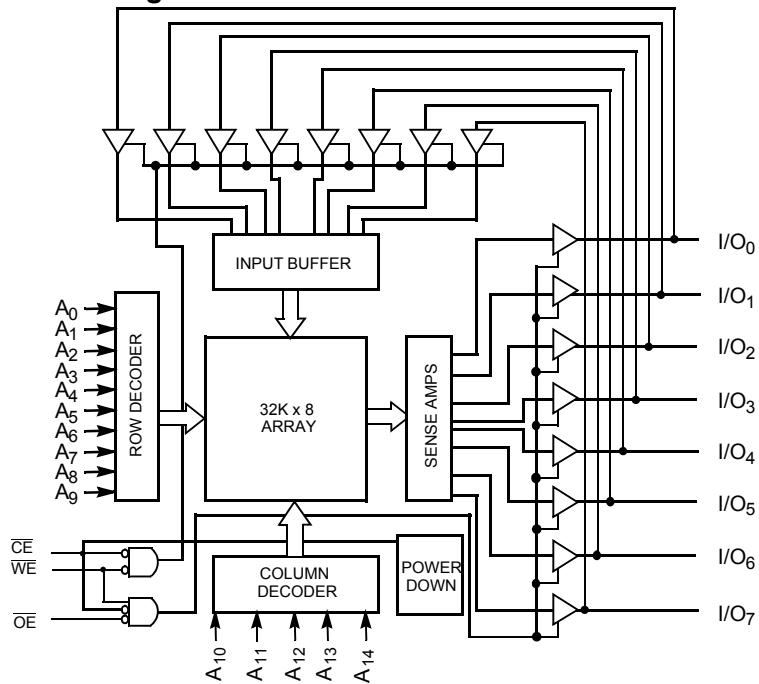
Functional Description

The WCFS0808V1E is a high-performance 3.3V CMOS Static RAM organized as 32K words by 8 bits. Easy memory expansion is provided by an active LOW Chip Enable (CE) and active LOW Output Enable (OE) and three-state drivers. The device has an automatic power-down feature, reducing the power consumption by more than 95% when deselected.

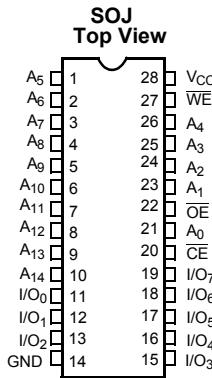
An active LOW Write Enable signal (\overline{WE}) controls the writing/reading operation of the memory. When CE and \overline{WE} inputs are both LOW, data on the eight data input/output pins (I/O₀ through I/O₇) is written into the memory location addressed by the address present on the address pins (A₀ through A₁₄). Reading the device is accomplished by selecting the device and enabling the outputs, CE and OE active LOW, while WE remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and Write Enable (WE) is HIGH. The WCFS0808V1E is available in 28-pin standard 300-mil-wide SOJ and TSOP Type I packages.

Logic Block Diagram



Pin Configurations



Selection Guide

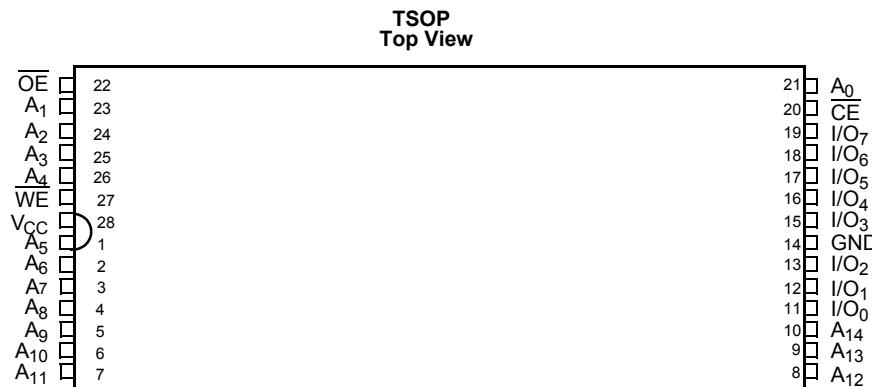
	WCFS0808V1E 12ns	WCFS0808V1E 15ns
Maximum Access Time (ns)	12	15
Maximum Operating Current (mA)	55	50
Maximum CMOS Standby Current (μA)	500	500



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WCFS0808V1E

Pin Configuration



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to $+150^{\circ}\text{C}$

Ambient Temperature with

Power Applied -55°C to $+125^{\circ}\text{C}$

Supply Voltage on V_{CC} to Relative GND^[1] -0.5V to $+4.6\text{V}$

DC Voltage Applied to Outputs
in High Z State^[1] -0.5V to $V_{\text{CC}} + 0.5\text{V}$

DC Input Voltage^[1] -0.5V to $V_{\text{CC}} + 0.5\text{V}$

Output Current into Outputs (LOW) 20 mA

Static Discharge Voltage $>2001\text{V}$
(per MIL-STD-883, Method 3015)

Latch-Up Current $>200\text{ mA}$

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to $+70^{\circ}\text{C}$	$3.3\text{V} \pm 300\text{ mV}$

Electrical Characteristics Over the Operating Range^[1]

Parameter	Description	Test Conditions	WCFS0808V1E 12ns		Unit
			Min.	Max.	
V_{OH}	Output HIGH Voltage	$V_{\text{CC}} = \text{Min.}$, $I_{\text{OH}} = -2.0\text{ mA}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{\text{CC}} = \text{Min.}$, $I_{\text{OL}} = 4.0\text{ mA}$		0.4	V
V_{IH}	Input HIGH Voltage		2.2	$V_{\text{CC}} + 0.3\text{V}$	V
V_{IL}	Input LOW Voltage		-0.3	0.8	V
I_{IX}	Input Load Current		-1	+1	μA
I_{OZ}	Output Leakage Current	$\text{GND} \leq V_{\text{I}} \leq V_{\text{CC}}$, Output Disabled	-5	+5	μA
I_{os}	Output Short Circuit Current ^[2]	$V_{\text{CC}} = \text{Max.}$, $V_{\text{OUT}} = \text{GND}$		-300	mA
I_{cc}	V_{CC} Operating Supply Current	$V_{\text{CC}} = \text{Max.}$, $I_{\text{OUT}} = 0\text{ mA}$, $f = f_{\text{MAX}} = 1/t_{\text{RC}}$		55	mA
I_{SB1}	Automatic CE Power-Down Current — TTL Inputs	$\text{Max. } V_{\text{CC}}, \overline{\text{CE}} \geq V_{\text{IH}}$, $V_{\text{IN}} \geq V_{\text{IH}}$ or $V_{\text{IN}} \leq V_{\text{IL}}$, $f = f_{\text{MAX}}$		5	mA
I_{SB2}	Automatic CE Power-Down Current — CMOS Inputs ^[3]	$\text{Max. } V_{\text{CC}}, \overline{\text{CE}} \geq V_{\text{CC}} - 0.3\text{V}$, $V_{\text{IN}} \geq V_{\text{CC}} - 0.3\text{V}$, or $V_{\text{IN}} \leq 0.3\text{V}$, $\text{WE} \geq V_{\text{CC}} - 0.3\text{V}$ or $\text{WE} \leq 0.3\text{V}$, $f = f_{\text{MAX}}$		500	μA

Notes:

1. Minimum voltage is equal to -2.0V for pulse durations of less than 20 ns.
2. Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
3. Device draws low standby current regardless of switching on the addresses.



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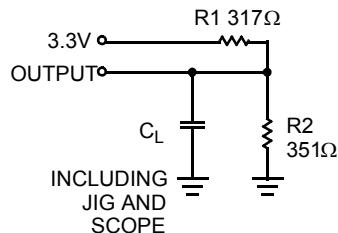
WCFS0808V1E

Electrical Characteristics Over the Operating Range (continued)

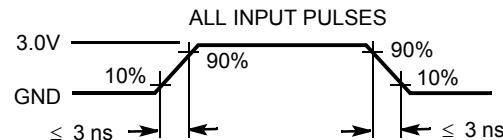
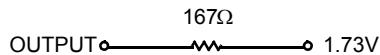
Parameter	Description	Test Conditions	WCFS0808V1E 15ns		Unit
			Min.	Max.	
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -2.0 mA	2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 4.0 mA		0.4	V
V _{IH}	Input HIGH Voltage		2.2	V _{CC} +0.3V	V
V _{IL}	Input LOW Voltage		-0.3	0.8	V
I _{IX}	Input Load Current		-1	+1	µA
I _{OZ}	Output Leakage Current	GND ≤ V _I ≤ V _{CC} , Output Disabled	-5	+5	µA
I _{OS}	Output Short Circuit Current ^[2]	V _{CC} = Max., V _{OUT} = GND		-300	mA
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max., I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC}		50	mA
I _{SB1}	Automatic CE Power-Down Current — TTL Inputs	Max. V _{CC} , C _E ≥ V _{IH} , V _{IN} ≥ V _{IH} , or V _{IN} ≤ V _{IL} , f = f _{MAX}		5	mA
I _{SB2}	Automatic CE Power-Down Current — CMOS Inputs ^[3]	Max. V _{CC} , C _E ≥ V _{CC} - 0.3V, V _{IN} ≥ V _{CC} - 0.3V, or V _{IN} ≤ 0.3V, WE ≥ V _{CC} - 0.3V or WE ≤ 0.3V, f = f _{MAX}		500	µA

Capacitance^[4]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN} : Addresses	Input Capacitance	T _A = 25°C, f = 1 MHz, V _{CC} = 3.3V	5	pF
C _{IN} : Controls			6	pF
C _{OUT}			6	pF

AC Test Loads and Waveforms

Equivalent to: THÉVENIN EQUIVALENT

**Note:**

4. Tested initially and after any design or process changes that may affect these parameters.



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WCFS0808V1E

Switching Characteristics Over the Operating Range^[5]

Parameter	Description	WCFS0808V1E 12ns		Unit
		Min.	Max.	
READ CYCLE				
t _{RC}	Read Cycle Time	12		ns
t _{AA}	Address to Data Valid		12	ns
t _{OHA}	Data Hold from Address Change	3		ns
t _{ACE}	CE LOW to Data Valid		12	ns
t _{DOE}	OE LOW to Data Valid		5	ns
t _{LZOE}	OE LOW to Low Z ^[6]	0		ns
t _{HZOE}	OE HIGH to High Z ^[6, 7]		5	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		ns
t _{HZCE}	CE HIGH to High Z ^[6, 7]		6	ns
t _{PU}	CE LOW to Power-Up	0		ns
t _{PD}	CE HIGH to Power-Down		12	ns
WRITE CYCLE ^[8, 9]				
t _{WC}	Write Cycle Time	12		ns
t _{SCE}	CE LOW to Write End	8		ns
t _{AW}	Address Set-Up to Write End	8		ns
t _{HA}	Address Hold from Write End	0		ns
t _{SA}	Address Set-Up to Write Start	0		ns
t _{PWE}	WE Pulse Width	8		ns
t _{SD}	Data Set-Up to Write End	7		ns
t _{HD}	Data Hold from Write End	0		ns
t _{HZWE}	WE LOW to High Z ^[8]		7	ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		ns

Notes:

5. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and capacitance C_L = 30 pF.
6. At any given temperature and voltage condition, t_{HZOE} is less than t_{LZOE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
7. t_{LZOE}, t_{LZCE}, t_{HZWE} are specified with C_L = 5 pF as in AC Test Loads. Transition is measured ± 500 mV from steady state voltage.
8. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
9. The minimum write cycle time for write cycle #3 (WE controlled, OE LOW) is the sum of t_{HZWE} and t_{SD}.



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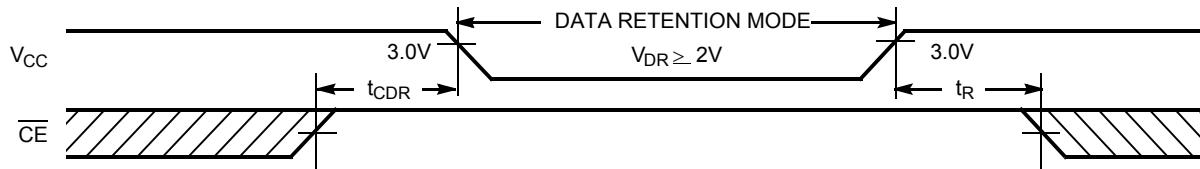
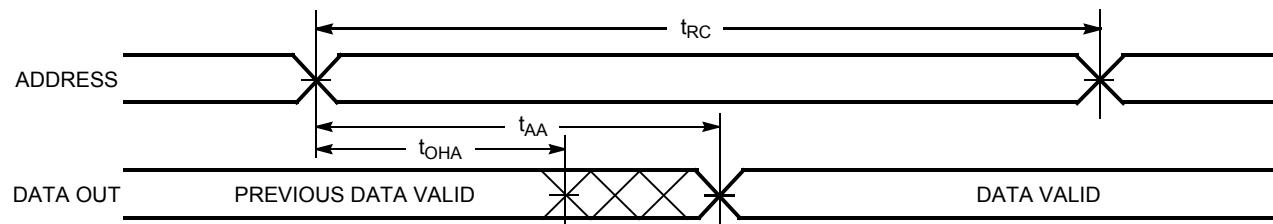
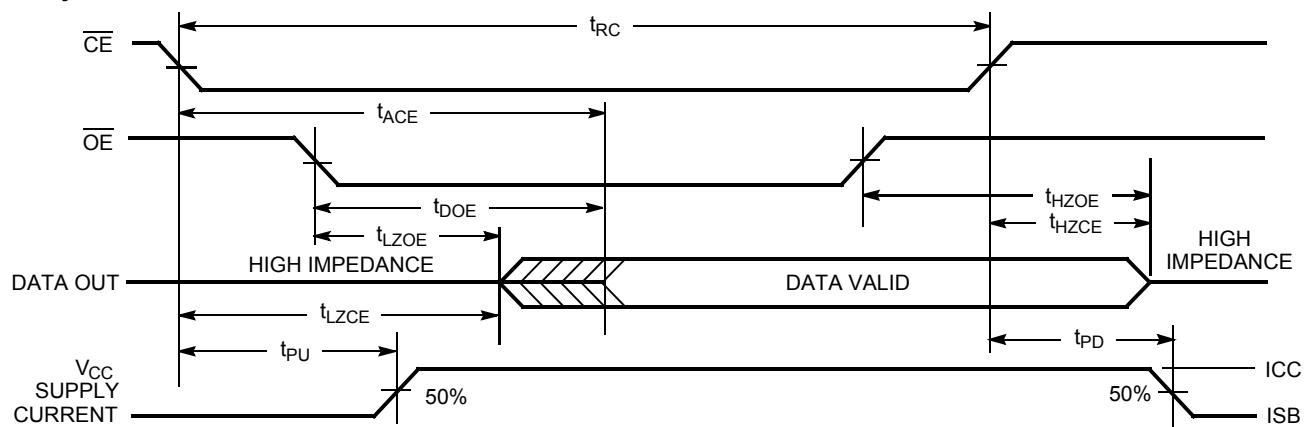
WCFS0808V1E

Switching Characteristics Over the Operating Range^[5] (Continued)

Parameter	Description	WCFS0808V1E 15ns		Unit
		Min.	Max.	
READ CYCLE				
t _{RC}	Read Cycle Time	15		ns
t _{AA}	Address to Data Valid		15	ns
t _{OHA}	Data Hold from Address Change	3		ns
t _{ACE}	CE LOW to Data Valid		15	ns
t _{DOE}	OE LOW to Data Valid		6	ns
t _{LZOE}	OE LOW to Low Z ^[6]	0		ns
t _{HZOE}	OE HIGH to High Z ^[6, 7]		6	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		ns
t _{HZCE}	CE HIGH to High Z ^[6, 7]		7	ns
t _{PU}	CE LOW to Power-Up	0		ns
t _{PD}	CE HIGH to Power-Down		15	ns
WRITE CYCLE ^[8, 9]				
t _{WC}	Write Cycle Time	15		ns
t _{SCE}	CE LOW to Write End	10		ns
t _{AW}	Address Set-Up to Write End	10		ns
t _{HA}	Address Hold from Write End	0		ns
t _{SA}	Address Set-Up to Write Start	0		ns
t _{PWE}	WE Pulse Width	10		ns
t _{SD}	Data Set-Up to Write End	8		ns
t _{HD}	Data Hold from Write End	0		ns
t _{HZWE}	WE LOW to High Z ^[8]		7	ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		ns

Data Retention Characteristics (Over the Operating Range)

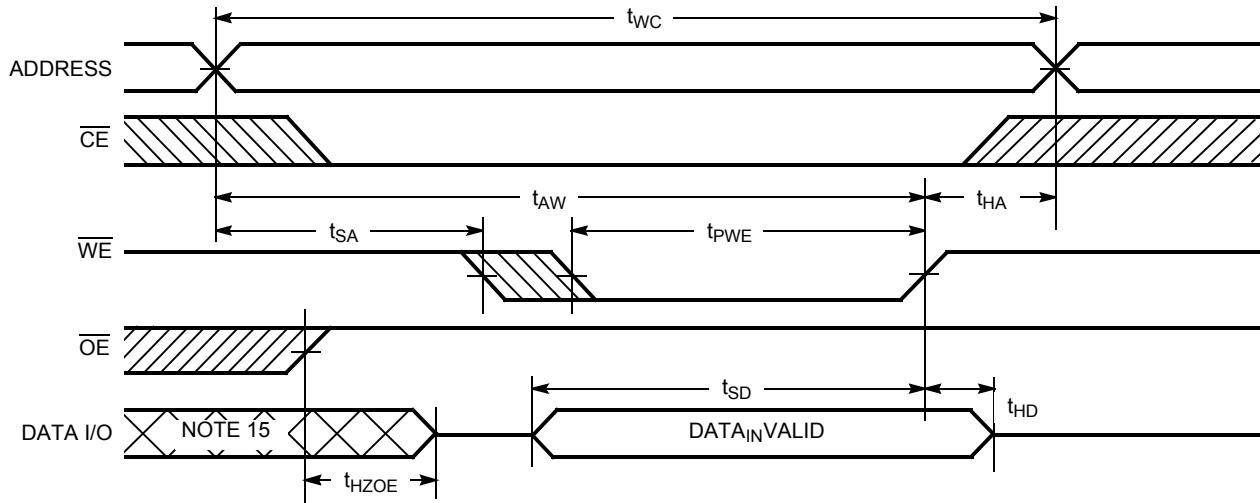
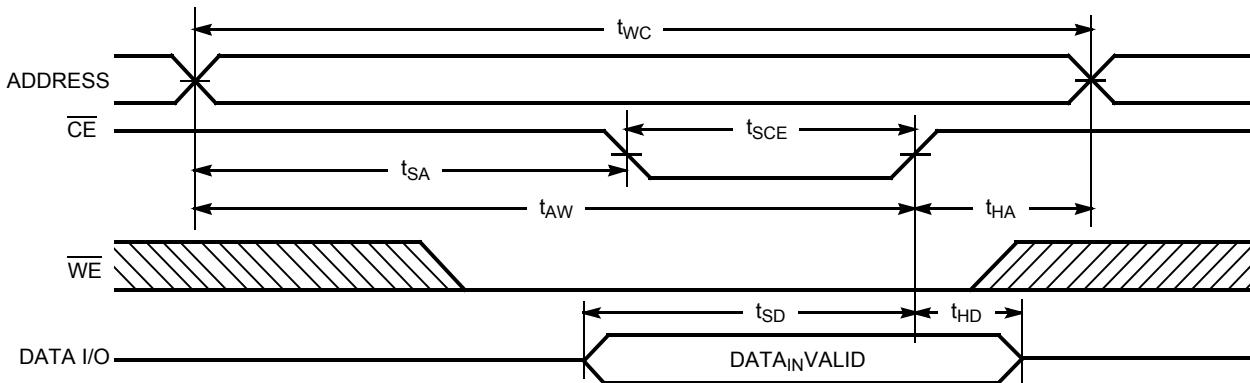
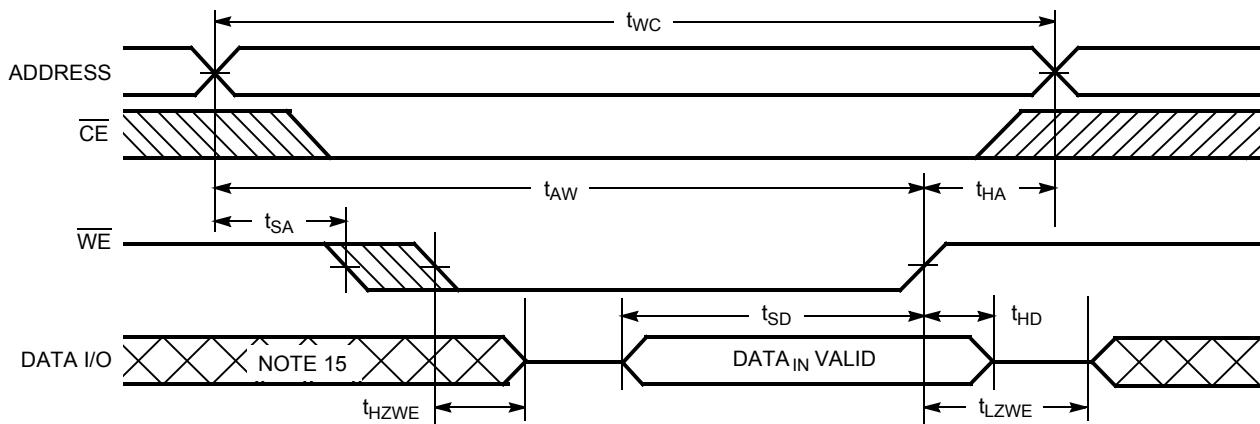
Parameter	Description	Conditions	Min.	Max.	Unit
V _{DR}	V _{CC} for Data Retention		2.0		V
t _{CDR}	Chip Deselect to Data Retention Time	V _{CC} = V _{DR} = 2.0V, CE ≥ V _{CC} - 0.3V, V _{IN} ≥ V _{CC} - 0.3V or V _{IN} ≤ 0.3V	0		ns
t _R	Operation Recovery Time		t _{RC}		ns

**Data Retention Waveform****Switching Waveforms****Read Cycle No. 1^[10, 11]****Read Cycle No. 2^[11, 12]****Notes:**

10. Device is continuously selected. \overline{OE} , \overline{CE} = V_{IL} .
11. WE is HIGH for read cycle.
12. Address valid prior to or coincident with \overline{CE} transition LOW.



Switching Waveforms (continued)

Write Cycle No. 1 ($\overline{\text{WE}}$ Controlled)^[8, 13, 14]Write Cycle No. 2 ($\overline{\text{CE}}$ Controlled)^[8, 13, 14]Write Cycle No. 3 ($\overline{\text{WE}}$ Controlled, $\overline{\text{OE}}$ LOW)^[9, 14]

Notes:

13. Data I/O is high impedance if $\overline{\text{OE}} = V_{IH}$.
14. If $\overline{\text{CE}}$ goes HIGH simultaneously with $\overline{\text{WE}}$ HIGH, the output remains in a high-impedance state.
15. During this period, the I/Os are in the output state and input signals should not be applied.



W E I D A

WCFS0808V1E

Truth Table

CE	WE	OE	Input/Output	Mode	Power
H	X	X	High Z	Deselect/Power-Down	Standby (I_{SB})
L	H	L	Data Out	Read	Active (I_{CC})
L	L	X	Data In	Write	Active (I_{CC})
L	H	H	High Z	Deselect, Output Disabled	Active (I_{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	WCFS0808V1E-JC12	J	28-Lead Molded SOJ	Commercial
15	WCFS0808V1E-JC15	J	28-Lead Molded SOJ	
	WCFS0808V1E-TC15	T	28-Lead Thin Small Outline Package	



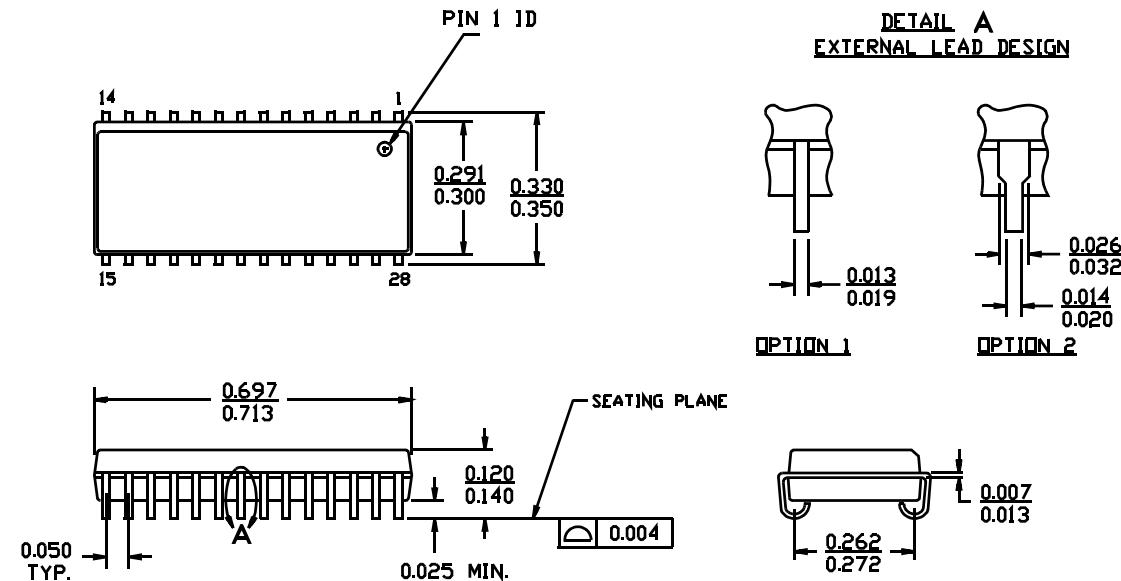
W E I D A

WCFS0808V1E

Package Diagrams

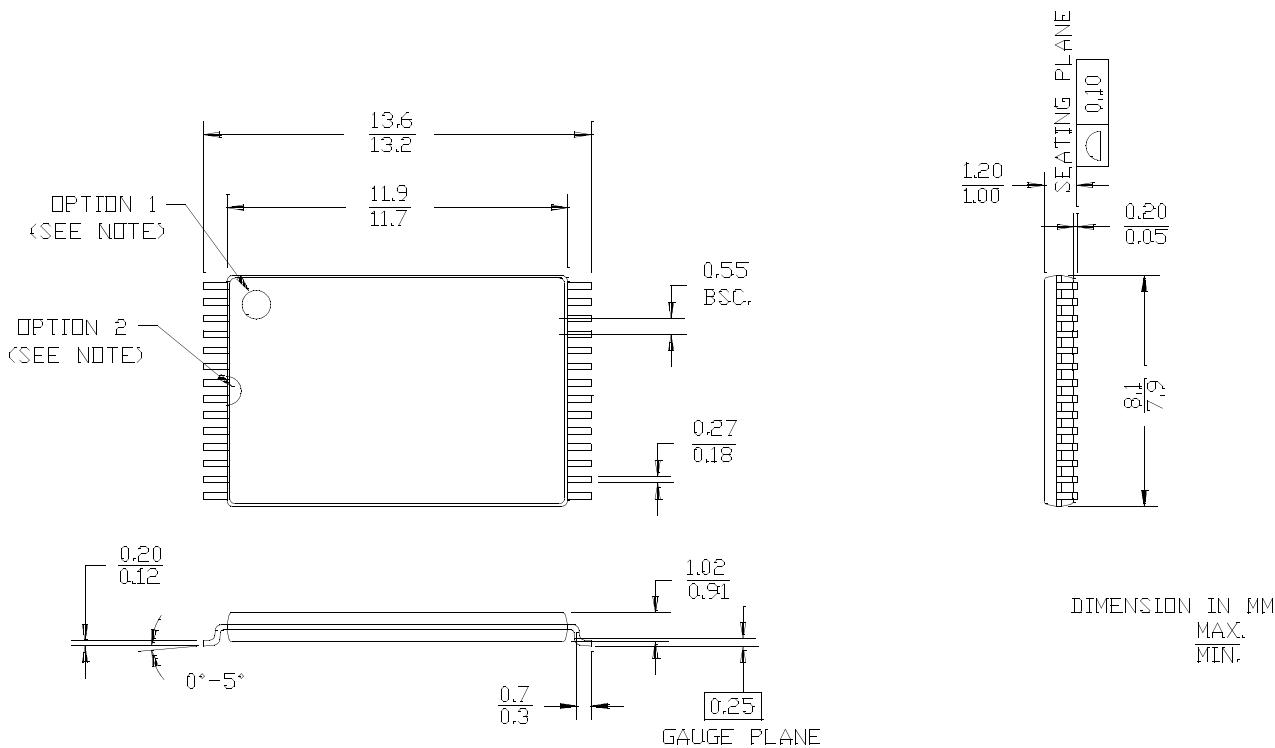
28-Lead (300-Mil) Molded SOJ J

DIMENSIONS IN INCHES MIN. MAX.



28-Lead Thin Small Outline Package Type 1 (8x13.4 mm) T

NOTE: ORIENTATION ID MAY BE LOCATED EITHER AS SHOWN IN OPTION 1 OR OPTION 2





W E I D A

WCFS0808V1E

Revision History

Document Title: WCFS0808V1E 32K x 8 3.3V Static RAM
Document Number: Document #: 38-05225 Rev. **

REV.	ECN NO.	ISSUE DATE	ORIG. OF CHANGE	DESCRIPTION OF CHANGE
**	113103	1/25/2002	XFL	New Datasheet



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